P.E. COMPANY

ELECTRONIC INFORMATION DISCLOSURE STATEMENT

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Title of Invention

ANOLYTE FOR COPPER PLATING

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First Named Applicant:

MICHAEL YANG

Attorney Docket Number: AMAT7669P2

Art Unit:

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(5224504 or 5489341 or 5573023 or 5620581

or 5731678 or 5744019 or 5837120 or 5883762 or 5996241 or 6014817 or 6099702 or 6099712 or 6126798 or 6132857 or 6136163 or 6156167 or 6179983 or 6228231 or 6228232 or 6248222

or 6254742 or 6261433 or 6267853 or 6273110 or 6280582 or 6322674 or 6322678 or 6368475 or 6374837 or 6383352 or 6391166 or 6395101 or 6395152 or 6409892 or 6432821 or 6436249 or 6440295 or 6527920 or 6551487 or 6569299

or 6589401 or 5252196 or 6197181 or 6290833

or 6319387 or 6334937 or 6551479 or 20020074233).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
LV	1	5224504	1993-07-06	THOMPSON, ET AL.			
	2	5489341	1996-02-06	BERGMAN, ET AL.			
	3	5573023	1996-11-12	THOMPSON, ET AL.	;		
	4	5620581	1997-04-15	ANG			
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LY	11	6099702	2000-08-08	REID, ET AL.
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	36	6436249	2002-08-20	PATTON, ET AL.
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	40	6569299	2003-05-27	REID, ET AL.
	41	6589401	2003-07-08	PATTON, ET AL.
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	43	6197181	2001-03-06	CHEN
	44	6290833	2001-09-18	CHEN
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Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
W	1	20020074233	2002-06-20	RITZDORF, ET AL.			

Signature

Examiner Name	Date
Jan Van	7/13/05